ISP1907
Built-in Antenna Bluetooth 5.1 Module
Multi-Protocol, Long Range & Direction Finding

This last generation BLE module is deployed in 2 variants to support complex or baseline applications requiring Bluetooth 5.1 standard for Long Range and Direction-Finding connectivity. At 8 x 8 x 1 mm, ISP1907 series provide huge computing capability coupled with best-in-class battery life, making this Bluetooth Low Energy / BLE module a ready to use solution for most of IOT applications.

Common Key Features
- Bluetooth 5.1 long-range direction-finding
- Thread / Zigbee / ANT+ stacks available
- Multi-protocol 2.4GHz low energy RF transceiver from nRF52 Nordic Semi family
- 32-bit ARM Cortex M4 CPU
- Many analog and digital IOs including ADC, SPI, UART, PDM, I2C
- Fully integrated RF matching and Antenna
- Embedded 32 MHz Radio & 32 kHz Synchro
- DC/DC converter including inductor
- Pin compatibility with iSP15, 18 & 19 series
- Integrated 32 MHz & 32 kHz Clocks
- Single 1.7 to 3.6 V supply
- Very small size 8.0 x 8.0 x 1.0 mm

LL Variant
- 192 kB Flash & 24 kB SRAM
- 13 Configurable GPIOs including 3 ADCs

HT Variant
- NFC-A Tag for OOB pairing
- ARM Cortex M4F Floating Point processor
- 512 kB Flash & 128 kB SRAM
- 30 Configurable GPIOs including 8 ADCs
- USB interface

Applications
- Connected sensors for medical devices, healthcare, sport, fitness, industrial …
- IoT applications, connected objects
- Wearable technology
- Home automation
- Beacons

Pending Certifications
- Bluetooth SIG listing
- Radio CE, FCC, IC, TELEC
- RoHS2, REACH, Conflict Minerals
## Revision History

<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Ref</th>
<th>Change Description</th>
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<tr>
<td>R0</td>
<td>26/06/2019</td>
<td>cr pg</td>
<td>Preliminary release</td>
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<tr>
<td>R1</td>
<td>10/01/2020</td>
<td>ys pg</td>
<td>Section 3 – HT variant pin description update</td>
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<tr>
<td>R2</td>
<td>28/01/2020</td>
<td>ys pg</td>
<td>Section 3 – Trace Data port added to HT variant</td>
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1. Block Diagram

This module is based on nRF52 Nordic Semiconductor 2.4GHz wireless System on Chip (SoC) integrating a 2.4 GHz transceiver, a 32-bit ARM Cortex™-M4 CPU, either 512 kB or 192 kB flash memory, either 128 kB RAM or 24 kB RAM and analog and digital peripherals.

It can support BLE, ANT/ANT+, Thread, Zigbee and a range of proprietary 2.4 GHz protocols, such as Gazell from Nordic Semiconductor.

Fully qualified BLE stacks for nRF52 are implemented in the S112/S132 SoftDevices which can be freely downloaded. ISP1907 can then be used in Central, Peripheral or both roles for BLE and for both ends of other proprietary protocols. nRF52 platform also provides extensive software support for Zigbee and Thread applications with nRF5 SDK, for ANT applications with S212/S312 SoftDevices.

Ultra-low power consumption and advanced power management enables battery lifetimes up to several years on a coin cell battery. Despite its very small size 8 x 8 x 1.0 mm, the module integrates decoupling capacitors, 32 MHz and 32.768 kHz crystals, DC-DC converter including the large inductor, RF matching circuit and antenna in addition to the wireless SoC.

Only the addition of a suitable DC power source is necessary for low energy connectivity. Sensor applications require the further addition of appropriate sensors. The antenna was designed to be optimized with several standard ground plane sizes. When NFC function is available, the NFC tag antenna can be connected externally.
2. Specifications

2.1. General Notice

The electrical specifications of the module are directly related to the Nordic Semiconductor specifications for nRF52 chipset series. The information below is only a summary of the main parameters. For more detailed information, especially about current consumption, please refer to the up-to-date specification of the chipset available on Nordic Semi website.

2.2. Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Main Supply Voltage respect to ground – VCC_nRF</td>
<td>-0.3</td>
<td>3.9</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>USB Supply Voltage respect to ground - VBUS</td>
<td>-0.3</td>
<td>5.8</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>IO Pin Voltage</td>
<td>-0.3</td>
<td>3.9</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>RF Input Level</td>
<td></td>
<td>10</td>
<td></td>
<td>dBm</td>
</tr>
<tr>
<td>NFC Antenna pin current</td>
<td></td>
<td>80</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Module Total Capacity</td>
<td></td>
<td>2.5</td>
<td></td>
<td>μF</td>
</tr>
<tr>
<td>Module Total Inductance</td>
<td></td>
<td>15</td>
<td></td>
<td>μH</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>-40</td>
<td>+125</td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td>Moisture Sensitivity Level</td>
<td></td>
<td>5</td>
<td></td>
<td>-</td>
</tr>
<tr>
<td>ESD Human Body Model</td>
<td></td>
<td>4000</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>ESD Charged Device Model</td>
<td></td>
<td>750</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Flash Endurance</td>
<td></td>
<td>10000</td>
<td></td>
<td>cycles</td>
</tr>
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**ATTENTION**

CONSERVE PRECAUTION FOR HANDLING ELECTROSTATIC SENSITIVE DEVICES
Human Body Model Class 3A

2.3. Operating Conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC_nRF Supply Voltage, independent of DCDC enable</td>
<td>1.7</td>
<td>3.0</td>
<td>3.6</td>
<td>V</td>
</tr>
<tr>
<td>VBUS Supply Voltage</td>
<td>4.35</td>
<td>5.0</td>
<td>5.5</td>
<td>V</td>
</tr>
<tr>
<td>Operating Temperature Range – LL Variant</td>
<td>-40</td>
<td>+25</td>
<td>+85</td>
<td>°C</td>
</tr>
<tr>
<td>Operating Temperature Range – HT Variant only</td>
<td>-40</td>
<td>+25</td>
<td>+105</td>
<td>°C</td>
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</table>
2.4. Power Consumption

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Typ / LL variant</th>
<th>Typ / HT variant</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Radio current, Receiver active</td>
<td>4.6</td>
<td>Not available</td>
<td>mA</td>
</tr>
<tr>
<td>Radio current, Transmitter active -40 dBm Output Power</td>
<td>3.4</td>
<td>Not available</td>
<td>mA</td>
</tr>
<tr>
<td>Peak current, Transmitter active 0 dBm Output Power</td>
<td>5.8</td>
<td>Not available</td>
<td>mA</td>
</tr>
<tr>
<td>System OFF, no RAM retention, wake on reset</td>
<td>0.3</td>
<td>Not available</td>
<td>µA</td>
</tr>
<tr>
<td>System ON, full RAM retention, wake on any event</td>
<td>0.8</td>
<td>Not available</td>
<td>µA</td>
</tr>
</tbody>
</table>

(1) DCDC enable, Power supply 3V, 1 Mbps

2.5. Clock Sources

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Internal High Frequency Clock for RF Stability: 32 MHz Crystal Frequency Tolerance</td>
<td>+/- 40</td>
<td>ppm</td>
</tr>
<tr>
<td>Internal Low Frequency Clock for BLE Synchronization: 32.768 kHz Crystal Frequency Tolerance</td>
<td>+/- 40</td>
<td>ppm</td>
</tr>
<tr>
<td>Internal Low Frequency Clock for BLE Synchronization: RC Oscillator</td>
<td>+/- 500</td>
<td>ppm</td>
</tr>
<tr>
<td>RF Frequency tolerance: For BLE operation Channels 0 to 39</td>
<td>+/- 40</td>
<td>ppm</td>
</tr>
</tbody>
</table>

(1) including initial tolerance, drift, aging, and frequency pulling
(2) Frequency tolerance after calibration

2.6. Radio Specifications

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating Frequencies</td>
<td>2360</td>
<td>2500</td>
<td>MHz</td>
<td></td>
</tr>
<tr>
<td>RF Channel spacing</td>
<td>125</td>
<td>2000</td>
<td>kbps</td>
<td></td>
</tr>
<tr>
<td>Data Rate</td>
<td>125</td>
<td>2000</td>
<td>kbps</td>
<td></td>
</tr>
<tr>
<td>RF Output Power, LL variant</td>
<td>-20</td>
<td>+4</td>
<td>dBm</td>
<td></td>
</tr>
<tr>
<td>RF Output Power, HT variant</td>
<td>-20</td>
<td>+8</td>
<td>dBm</td>
<td></td>
</tr>
<tr>
<td>Rx sensitivity Level 1 Mbps BLE mode, ideal Tx</td>
<td>-94</td>
<td></td>
<td>dBm</td>
<td></td>
</tr>
<tr>
<td>Rx sensitivity Level 125 kbps Long Range mode, ideal Tx</td>
<td>-104</td>
<td></td>
<td>dBm</td>
<td></td>
</tr>
<tr>
<td>Antenna Gain</td>
<td>0.6</td>
<td></td>
<td>dBi</td>
<td></td>
</tr>
<tr>
<td>Range Open field, BLE mode @1m height</td>
<td>100</td>
<td></td>
<td>m</td>
<td></td>
</tr>
<tr>
<td>Range Open field, Long Range mode +4 dBm @1m height</td>
<td>400</td>
<td></td>
<td>m</td>
<td></td>
</tr>
</tbody>
</table>
Typical Antenna Return Loss

Module mounted on a USB dongle ground plane

![Graph showing dB(S11) vs freq, GHz]

**Radiation Pattern in 3 planes**

Module mounted on a USB dongle ground plane

![3D diagram illustrating radiation pattern]

**Gain measurement in dBi @ 2.45 GHz.**
Ground Plane Effect Simulation

USB dongle ground plane (size: 18 x 30 mm²)

Cell phone config 1 ground plane (size: 40 x 100 mm²)

Cell phone config 1 with side ground plane (size: 40 x 100 mm²)

Cell phone config 2 with side ground plane (size: 40 x 100 mm²)

Cell phone config 3 with side ground plane (size: 40 x 100 mm²)

Return loss, dB

freq, GHz
2.7. Electrical Schematic

LL variant

Hereafter electrical schematic is showing ISP1907-LL module connections. For further information on electrical performance, please note that LL variant is based on nRF52811 chipset.

HT variant

Schematic not available yet. Please consult us for more information.
### 3. Pin Description

The module uses an LGA format with multiple rows of pads on a 0.65 mm pitch. The pad layout follows the QFN Jedec standard for 2 row LGA parts. The NC pads are to be connected to isolated metal pads on the application PCB for mechanical stability and reliability (drop test).

<table>
<thead>
<tr>
<th>Pin</th>
<th>Description for LL variant</th>
<th>Description for HT variant</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>2</td>
<td>P0_12</td>
<td>General purpose I/O pin</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>NC</td>
<td>Isolated pad</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>4</td>
<td>P0_14</td>
<td>General purpose I/O pin</td>
</tr>
<tr>
<td></td>
<td>TRACEDATA3</td>
<td>Trace port output</td>
</tr>
<tr>
<td>5</td>
<td>NC</td>
<td>Isolated pad</td>
</tr>
<tr>
<td>6</td>
<td>P0_18</td>
<td>General purpose I/O pin</td>
</tr>
<tr>
<td></td>
<td>TRACEDATA0</td>
<td>Trace port output</td>
</tr>
<tr>
<td>7</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>8</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>9</td>
<td>P0_16</td>
<td>General purpose I/O pin</td>
</tr>
<tr>
<td></td>
<td>TRACEDATA1</td>
<td>Trace port output</td>
</tr>
<tr>
<td>10</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>11</td>
<td>NC</td>
<td>Isolated pad</td>
</tr>
<tr>
<td>12</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>13</td>
<td>P0_21</td>
<td>General purpose I/O pin</td>
</tr>
<tr>
<td></td>
<td>RESET</td>
<td>Configurable as system RESET pin</td>
</tr>
<tr>
<td>14</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>15</td>
<td>NC</td>
<td>Isolated pad</td>
</tr>
<tr>
<td>16</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
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<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>17</td>
<td>NC</td>
<td>Isolated pad</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>18</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>19</td>
<td>P0_20</td>
<td>General purpose I/O pin</td>
</tr>
<tr>
<td></td>
<td>TRACECLK</td>
<td>Trace port clock output</td>
</tr>
<tr>
<td>20</td>
<td>OUT_ANT</td>
<td>This pin is connected to</td>
</tr>
<tr>
<td></td>
<td></td>
<td>the internal antenna</td>
</tr>
<tr>
<td></td>
<td></td>
<td>It should be connected to</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Pin 22</td>
</tr>
<tr>
<td></td>
<td></td>
<td>OUT_MOD for normal operation</td>
</tr>
<tr>
<td>21</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>22</td>
<td>OUT_MOD</td>
<td>This pin is the RF I/O pin</td>
</tr>
<tr>
<td></td>
<td></td>
<td>of the BLE module</td>
</tr>
<tr>
<td></td>
<td></td>
<td>It should be connected to</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Pin 20</td>
</tr>
<tr>
<td></td>
<td></td>
<td>OUT_ANT for normal operation</td>
</tr>
<tr>
<td>23</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>24</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>25</td>
<td>VSS</td>
<td>Must be connected to ground</td>
</tr>
<tr>
<td>Pin</td>
<td>Description for LL variant</td>
<td>Description for HT variant</td>
</tr>
<tr>
<td>-----</td>
<td>----------------------------</td>
<td>----------------------------</td>
</tr>
<tr>
<td>26</td>
<td>VCC_nRF Power supply (1.7 – 3.6V)</td>
<td>VCC_nRF Power supply (1.7 – 3.6V)</td>
</tr>
<tr>
<td>27</td>
<td>NC Isolated pad</td>
<td>P0_17 General purpose I/O pin</td>
</tr>
<tr>
<td>28</td>
<td>SWDIO Serial Wire Debug I/O for debug and programming</td>
<td>SWDIO Serial Wire Debug I/O for debug and programming</td>
</tr>
<tr>
<td>29</td>
<td>NC Isolated pad</td>
<td>P0_13 General purpose I/O pin</td>
</tr>
<tr>
<td>30</td>
<td>SWDCLK Serial Wire Debug clock input for debug and programming</td>
<td>SWDCLK Serial Wire Debug clock input for debug and programming</td>
</tr>
<tr>
<td>31</td>
<td>VSS Must be connected to ground</td>
<td>VSS Must be connected to ground</td>
</tr>
<tr>
<td>32</td>
<td>P0_08 General purpose I/O pin</td>
<td>P0_08 General purpose I/O pin</td>
</tr>
<tr>
<td>33</td>
<td>NC Isolated pad</td>
<td>P0_07 TRACECLK General purpose I/O pin Trace port clock output</td>
</tr>
<tr>
<td>34</td>
<td>P0_17 General purpose I/O pin</td>
<td>P0_06 General purpose I/O pin</td>
</tr>
<tr>
<td>35</td>
<td>NC Isolated pad</td>
<td>P0_04 AIN2 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>36</td>
<td>P0_05 AIN3 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
<td>P0_05 AIN3 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>37</td>
<td>NC Isolated pad</td>
<td>P1_09 TRACEDATA3 General purpose I/O pin Trace port output</td>
</tr>
<tr>
<td>38</td>
<td>P0_03 AIN1 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
<td>P0_03 AIN1 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>39</td>
<td>NC Isolated pad</td>
<td>P0_27 General purpose I/O pin</td>
</tr>
<tr>
<td>40</td>
<td>P0_01 XL2 Do not connect – Leave floating</td>
<td>P0_02 AIN0 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>41</td>
<td>NC Isolated pad</td>
<td>P0_25 General purpose I/O pin</td>
</tr>
<tr>
<td>42</td>
<td>P0_00 XL1 Do not connect – Leave floating</td>
<td>P0_31 AIN7 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>43</td>
<td>NC Isolated pad</td>
<td>P0_11 TRACEDATA2 General purpose I/O pin Trace port output</td>
</tr>
<tr>
<td>44</td>
<td>P0_15 TRACEDATA2 General purpose I/O pin Trace port output</td>
<td>P0_30 AIN6 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>45</td>
<td>NC Isolated pad</td>
<td>P0_19 General purpose I/O pin</td>
</tr>
<tr>
<td>46</td>
<td>P0_04 AIN2 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
<td>P0_29 AIN5 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>47</td>
<td>NC Isolated pad</td>
<td>P0_23 General purpose I/O pin</td>
</tr>
<tr>
<td>48</td>
<td>P0_11 General purpose I/O pin</td>
<td>P0_28 AIN4 General purpose I/O pin SAADC/COMP/LPCOMP input</td>
</tr>
<tr>
<td>49</td>
<td>NC Isolated pad</td>
<td>NC Isolated pad</td>
</tr>
<tr>
<td>50</td>
<td>to 62 NC Isolated pad</td>
<td>NC Isolated pad</td>
</tr>
</tbody>
</table>
ISP1907
62-pin LGA QFN package

pad placement and pin assignment

TOP VIEW
4. Mechanical Outlines

4.1. Mechanical Dimensions

Dimensional drawing for 8 x 8 x 1 mm, 62-Pad LGA Package
4.2. SMT Assembly Guidelines

For PCB Land Patterns and Solder Mask layout, Insight SiP recommends to use the same dimensions as module pads, ie 0.4 x 0.4 mm for standard pads and 0.8 x 0.8 mm for corner pads.

Please contact Insight SiP for more detailed information.

4.3. Antenna Keep-Out Zone

For optimal antenna performance, it is recommended to respect a metal exclusion zone to the edge of the board: no metal, no traces and no components on any application PCB layer except mechanical LGA pads.
5. Product Development Tools

5.1. Hardware

In order to assist clients in developing their Bluetooth Smart solutions based on the ISP1907, Insight SIP offers an Evaluation Board containing:
- One Interface Board with J-Link Seeger integrated SWD/JTAG interface
- One Test Board
- Cables
- NFC Antenna (for the ISP1907-HT version)

Using this evaluation board, product developers can use a working solution as a starting point to develop their own products. Time to market is saved by avoiding starting from a blank sheet of paper.

Please refer to the documentation for more information:

5.2. Firmware

ISP1907 supports Bluetooth Low Energy protocol stacks, ANT protocol stacks as well as 2.4 GHz protocol stacks, including Gazell. For more details regarding SoftDevice stacks and their compatibility with ISP1907 module version, please refer to the Nordic info center at www.infocenter.nordicsemi.com. All stacks can be downloaded at www.nordicsemi.com.

Even though any module version can support any stack, the S112 stack described hereunder is perfectly suited for ISP1907-LL version while S132, S212 and S332 are more dedicated to ISP1907-HT version.

- The S112 SoftDevice is a Bluetooth low energy peripheral protocol stack solution. It supports up to four peripheral connections with an additional broadcaster role running concurrently. The S112 SoftDevice integrates a Bluetooth low energy Controller and Host and provides a full and flexible API for building Bluetooth low energy ISP1907 solutions.

- The S132 SoftDevice is a Bluetooth low energy Central and Peripheral protocol stack solution. It supports up to twenty connections with an additional observer and a broadcaster role all running concurrently. The S132 SoftDevice integrates a Bluetooth low energy Controller and Host and provides a full and flexible API for building Bluetooth low energy ISP1907 solutions.

- The S212 SoftDevice is an ANT protocol stack solution that provides a full and flexible Application Programming Interface (API) for building ANT System on ISP1907 solutions. The S212 SoftDevice simplifies combining the ANT protocol stack and an application on the same CPU.

- The S332 SoftDevice is a combined ANT™ and Bluetooth low energy (BLE) protocol stack solution. It supports all four Bluetooth low energy roles (Central, Peripheral, Observer, Broadcaster) and ANT.
5.3. Development Tools

The following development tools and software are recommended for using and testing ISP1907 module:

- **Nordic Semiconductor nRFgo Studio:**

- **Nordic Semiconductor Master Control Panel:**
  Downloadable after registering at [www.nordicsemi.com](http://www.nordicsemi.com).
  An alternative remains to use the “nRF Connect” application for Smartphone available on the App Store (iOS device) and on the Play Store (Android device).

- **Debugging and IDE:**
  - SEGGER Embedded Studio (SES):
  - Keil MDK-ARM Lite (limited to 32 KB code)
    Downloadable from [https://www.keil.com/demo/eval/arm.htm](https://www.keil.com/demo/eval/arm.htm).
  - Segger J-Link Lite:

- **nRF52 Software Development Kit (SDK):**
  nRF5-SDK can be downloaded after registering at www.nordicsemi.com. It contains example of source codes applications (C language):
  - Precompiled HEX files
  - Source code
  - SES project files
  - Keil ARM project files
  - IAR project files
6. Packaging & Ordering information

6.1. Marking

<table>
<thead>
<tr>
<th>M/N : ISP 1907</th>
</tr>
</thead>
<tbody>
<tr>
<td>TT YY WW R</td>
</tr>
</tbody>
</table>

ISP1907 | Part Number |
<table>
<thead>
<tr>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>TT</td>
<td>2 letters Module Type (see section 6.5)</td>
</tr>
<tr>
<td>YY</td>
<td>2 digits year number</td>
</tr>
<tr>
<td>WW</td>
<td>2 digits week number</td>
</tr>
<tr>
<td>R</td>
<td>1 letter Hardware revision</td>
</tr>
</tbody>
</table>

6.2. Prototype Packaging

For engineering samples and prototype quantities up to 99 units, deliveries are provided in thermoformed trays or cut tapes.

They are delivered in sealed pack with desiccant pack and humidity sensors. Please see section 7.2 for more information on moisture sensitivity.

Please order with “ST” code packaging suffix.

6.3. Jedec Trays

For pre-production volumes, ISP1907 are available in Jedec trays. They are delivered in sealed pack with desiccant pack and humidity sensors. These Jedec trays are also suitable for further baking. Please see section 7.2 for more information on moisture sensitivity.

Please order with “JT” code packaging suffix.

Refer to tray sizes below. Complete information on Jedec trays is available on request.
6.4. Tape and Reel

ISP1907 are also available in Tape & Reel. They are delivered in sealed pack with desiccant pack and humidity sensors. Reels are proposed in standard quantities of 500 units (180mm / 7” reel) or 2000 units (330mm / 13” reel) only. Please order with “RS” code packaging suffix for 500-unit reels and “R2” for 2000-unit reels.
### 6.5. Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>192 kB Flash / 24 kB RAM memory type</th>
<th>512 kB Flash / 128 kB RAM memory type</th>
</tr>
</thead>
<tbody>
<tr>
<td>ISP1907</td>
<td>Evaluation Board</td>
<td>Test board</td>
</tr>
<tr>
<td>L L</td>
<td></td>
<td>Tray or Cut Tape</td>
</tr>
<tr>
<td>H T</td>
<td></td>
<td>Jedec Tray Packaging</td>
</tr>
<tr>
<td>E B</td>
<td></td>
<td>Reel of 500 units</td>
</tr>
<tr>
<td>T B</td>
<td></td>
<td></td>
</tr>
<tr>
<td>S T</td>
<td></td>
<td></td>
</tr>
<tr>
<td>J T</td>
<td></td>
<td></td>
</tr>
<tr>
<td>R S</td>
<td></td>
<td></td>
</tr>
<tr>
<td>R 2</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
7. Storage & Soldering information

7.1. Storage and Handling

Keep this product away from other high frequency devices which may interfere with operation such as other transmitters and devices generating high frequencies.

Do not expose the module to the following conditions:
- Corrosive gasses such as Cl2, H2S, NH3, SO2, or NOX
- Extreme humidity or salty air
- Prolonged exposure to direct Sunlight
- Temperatures beyond those specified for storage

Do not apply mechanical stress

Do not drop or shock the module

Avoid static electricity, ESD and high voltage as these may damage the module

ATTENTION
CONSERVE PRECAUTION FOR HANDLING ELECTROSTATIC SENSITIVE DEVICES

7.2. Moisture Sensitivity

All plastic packages absorb moisture. During typical solder reflow operations when SMDs are mounted onto a PCB, the entire PCB and device population are exposed to a rapid change in ambient temperature. Any absorbed moisture is quickly turned into superheated steam. This sudden change in vapor pressure can cause the package to swell. If the pressure exerted exceeds the flexural strength of the plastic mold compound, then it is possible to crack the package. Even if the package does not crack, interfacial delamination can occur.

Since the device package is sensitive to moisture absorption, it is recommended to bake the product before assembly. The baking process for dry packing is 24 hours at 125°C.

ISP1907 has been tested MSL-3 according to standards. After baking, modules can be exposed to ambient room conditions (approximately 30 °C/60%RH) during 168 hours before assembly on the PCB.
7.3. Soldering information

Recommendation for RoHS reflow process is according to Jedec J–STD-020 and 033 standard profiles.

<table>
<thead>
<tr>
<th>Preheat/Soak</th>
<th>Temperature Min ($T_{\text{min}}$)</th>
<th>Temperature Max ($T_{\text{max}}$)</th>
<th>Time ($t_s$) from ($T_{\text{min}}$ to $T_{\text{max}}$)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>150 °C</td>
<td>200 °C</td>
<td>60-120 sec</td>
</tr>
</tbody>
</table>

Ramp-up rate ($T_{L}$ to $T_P$) 3 °C/sec max

Liquidous temperature ($T_L$) 217 °C
Time ($t_L$) maintained above $T_L$ 60-150 sec

Peak package body temperature ($T_P$) 260°C (+0/-5°C)
Classification Temperature ($T_C$) 260 °C
Time ($t_C$) maintained above $T_C$-5 °C 30 sec
Ramp-down rate ($T_P$ to $T_L$) 6 °C/sec max
Time 25 °C to peak temperature 8 mn max
8. Quality & User information

8.1. Certifications

- FCC Identifier pending
- CE: Complies with 1999/5/EC, EN300328 V1.9.1 – EC DoC pending
- IC– Certification pending
- TELEC certification pending
- Bluetooth SIG certified pending
- RoHS compliant

8.2. USA – User information

This intends to inform how to specify the FCC ID of our module “ISP1907” on the product. Based on the Public Notice from FCC, the host device should have a label which indicates that it contains our module. The label should use wording such as:

```
“Contains FCC ID: 2AAQS-ISP1907”
```

Any similar wording that expresses the same meaning may be used.

The label of the host device should also include the below FCC Statement. When it is not possible, this information should be included in the User Manual of the host device:

```
“This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions.
(1) This device may not cause harmful interference
(2) This device must accept any interference received, including interference that may cause undesired operation.
Caution: Any Changes or modifications not expressly approved by the party responsible for compliance could void the user’s authority to operate the equipment.”
```

8.3. Canada – User information

This intends to inform how to specify the IC ID of our module “ISP1907” on the product. According to Canadian standards “RSS-210” and “RSS-Gen”, the host device should have a label which indicates that it contains our module. The label should use wording such as:

```
“Contains IC: 11306A-ISP1907”
```

Any similar wording that expresses the same meaning may be used.
The label of the host device should also include the below IC Statement. When it is not possible, this information should be included in the User Manual of the host device:

"This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement."

8.4. RF Exposure Information

This equipment complies with FCC/IC radiation exposure limits set forth for an uncontrolled environment and meets the FCC radio frequency (RF) Exposure Guidelines in Supplement C to OET65 and RSS-102 of the IC radio frequency (RF) Exposure rules. This equipment has very low levels of RF energy that it deemed to comply without maximum permissive exposure evaluation (MPE).

8.5. Informations concernant l'exposition aux fréquences radio (RF)

La puissance de sortie émise par l'appareil de sans-fil est inférieure à la limite d'exposition aux fréquences radio d'Industry Canada (IC). Ce module a également été évalué et démontré conforme aux limites d'exposition aux RF d'IC dans des conditions d'exposition à des appareils mobiles et/ou portables.

8.6. Discontinuity

Normally a product will continue to be manufactured as long as all of the following are true:
- The manufacturing method is still available.
- There are no replacement products.
- There is demand for it in the market.

In case of obsolescence, Insight SiP will follow Jedec Standard JSD-48. A Product Discontinuation Notice (PDN) will be sent to all distributors and made available on our website. After this, the procedure goes as follows:
- Last Order Date will be 6 months after the PDN was published.
- Last Shipment Date will be 6 months after Last Order Date, i.e. 12 months after PDN.
8.7. Disclaimer

Insight SiP’s products are designed and manufactured for general consumer applications, so testing and use of the product shall be conducted at customer’s own risk and responsibility. Please conduct validation and verification and sufficient reliability evaluation of the products in actual condition of mounting and operating environment before commercial shipment of the equipment. Please also pay attention (i) to apply soldering method that don’t deteriorate reliability, (ii) to minimize any mechanical vibration, shock, exposure to any static electricity, (iii) not to overstress the product during and after the soldering process.

The products are not designed for use in any application which requires especially high reliability where malfunction of these products can reasonably be expected to result in personal injury or damage to the third party's life, body or property, including and not limited to (i) aircraft equipment, (ii) aerospace equipment, (iii) undersea equipment, (iv) power plant control equipment, (v) medical equipment, (vi) transportation equipment, (vii) traffic signal equipment, (viii) disaster prevention / crime prevention equipment.

The only warranty that Insight SiP provides regarding the products is its conformance to specifications provided in datasheets. Insight SiP hereby disclaims all other warranties regarding the products, express or implied, including without limitation any warranty of fitness for a particular purpose, that they are defect-free, or against infringement of intellectual property rights. Insight SiP customers agree to indemnify and defend Insight SiP against all claims, damages, costs and expenses that may be incurred, including without any limitation, attorney fees and costs, due to the use of products.